Manufacturing Status Review

Customer:

Scott Taylor,
Surrey Satellite Technology
U.S.



PAB Advisor:Josh Stamps,

Sierra Nevada Corporation

Presenting: Anthony Anglin, Lindsay Goldworm, Elizabeth Luke, Nicholaus Monahan, Mary Scites

Other Team Members: Aspen Coates, Emmett Bailey, Zach McConnel, Sierra Williams

Overview

Motivation – Star tracker baffles

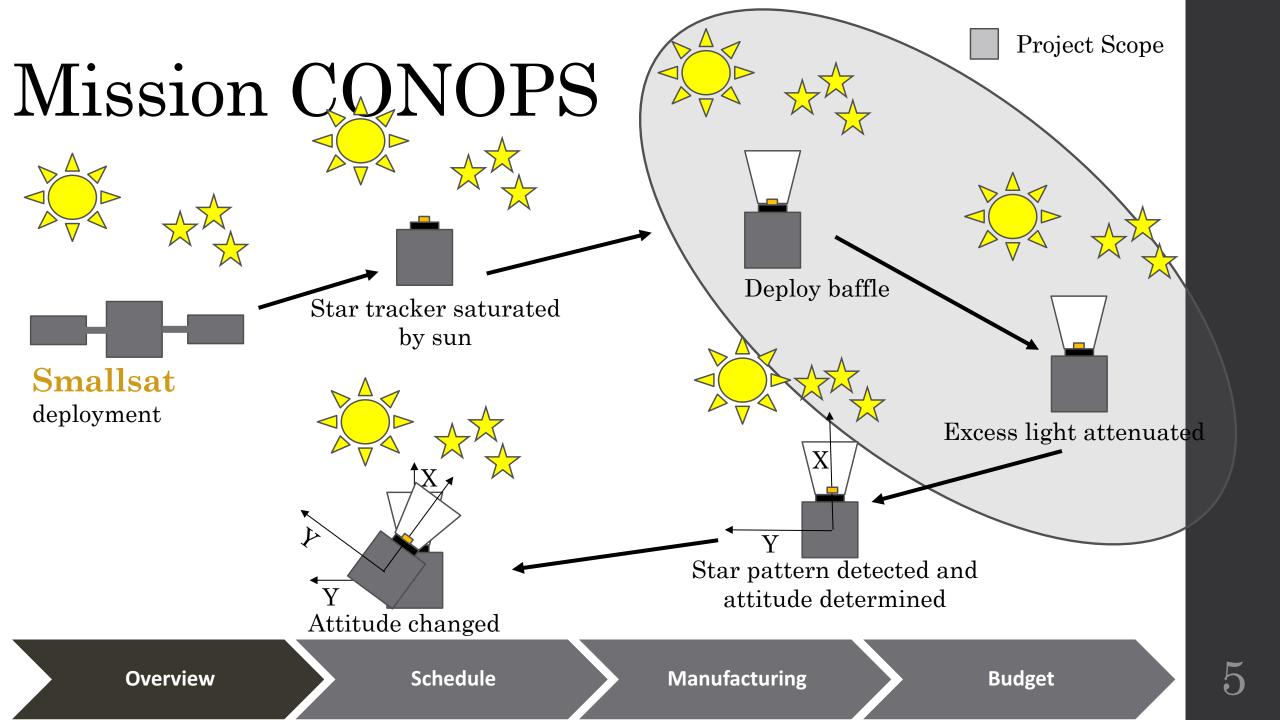
- Star trackers need to see dim light from distant stars
- They compare what they see with on board star catalog to make spacecraft attitude adjustments
- Nearby bodies emit/reflect stray light which hinders star trackers ability to see dim light
- Baffles attenuate and eliminate stray light from nearby bodies
- Lightweight deployable baffle for smallsats

Project Goals

•Develop a prototype deployable baffle for a star tracker to be used on a small satellite platform

- Design and manufacture a deployable baffle to limit stray light into an optical sensor
- •Develop a test methodology and instrumentation suite to measure performance of the baffle for stray light elimination

Perform the tests for the deployment and stray light elimination of the baffle

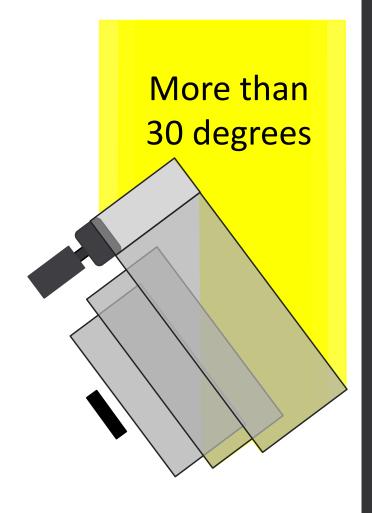


Project CONOPS - Deployment

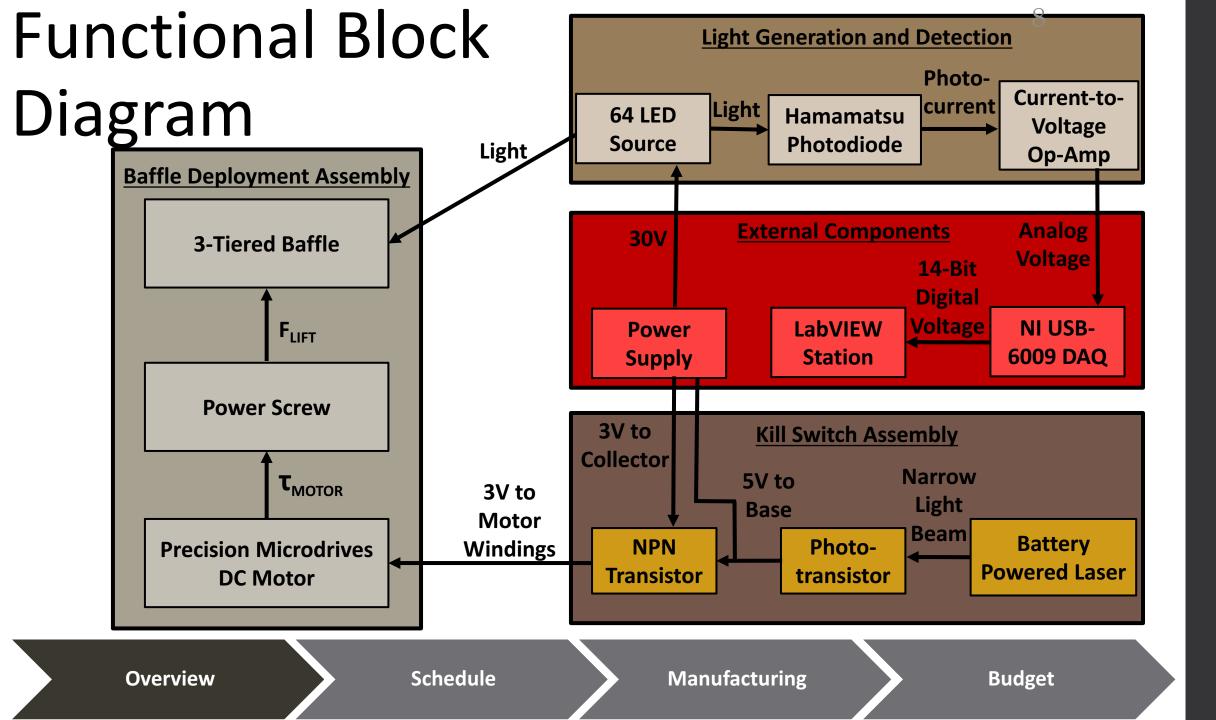


Project CONOPS – Light

Attenuation 10 to 15 0 degrees degrees Sensor



* In testing the sensor will not be displaced from the baffle



Requirements & Levels of Success

•FR1: Baffle shall be deployable

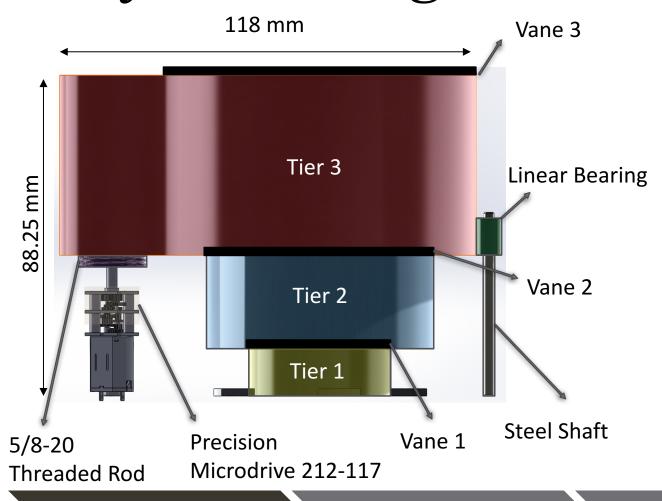
•FR2: Baffle shall fit within volume constraints

•FR3: Baffle shall adhere to mass constraints

•FR4: Baffle shall attenuate light

	TIER 2
DEPLOY BAFFLE (FR1)	Electronic deployment with a wired connection
STOWED BAFFLE VOLUME (FR2)	Constrained by: 125 mm width 125 mm length 50 mm height
BAFFLE MASS (FR3)	<300 grams
BAFFLE LIGHT EXCLUSION (FR4)	30 degree light exclusion angle

Baseline Design From CDR & Major Changes



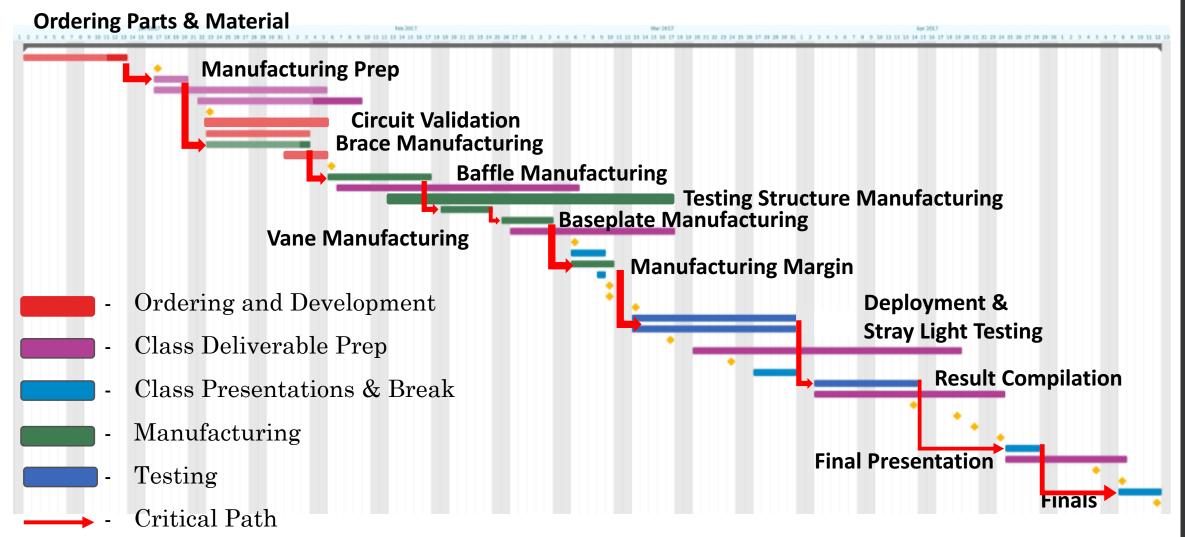
No Major Structural Changes Between CDR and MSR

CPEs & Manufacturing Challenges

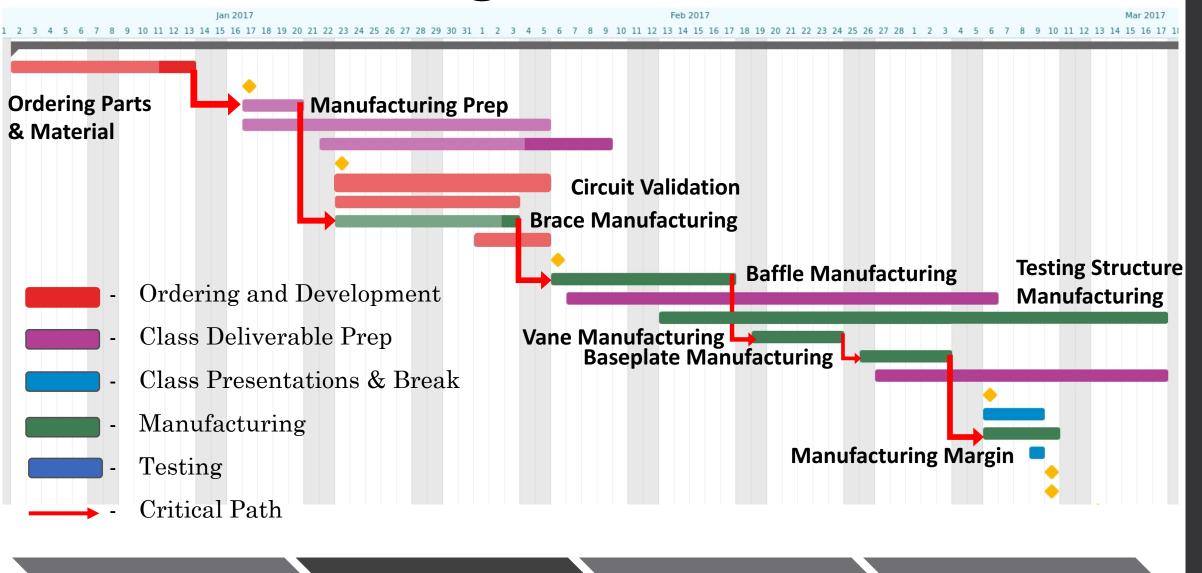
СРЕ	Project Integration	Manufacturing Challenges	
Deployment (FR1-3)	 Electrical Interface Mechanical Integration Manufacturing Baffle Challenges & Tolerances 	PCB creationTime Intensive	
Light Attenuation (FR4)	Manufacturing Vane TolerancesSimulation Accuracy	 Bending/warping sheet metal 	
Testing (FR1&4)	 Electrical Interface Mechanical Integration Manufacturing Testing Parts Simulation Accuracy and Precision 	• Complex	

Schedule

Overall Schedule



Manufacturing Schedule



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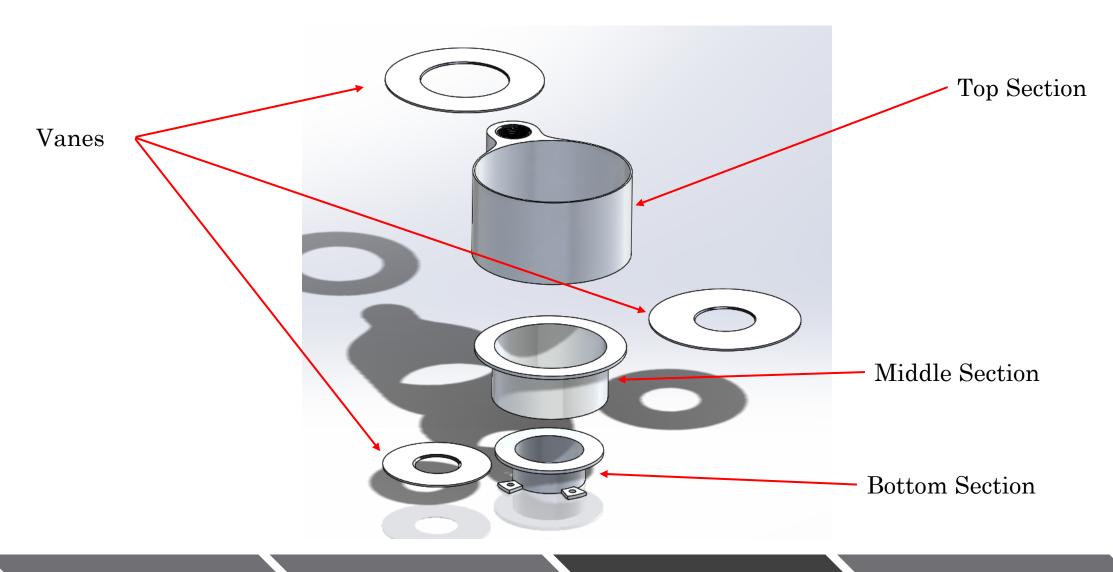
Budget

Scheduling Concerns

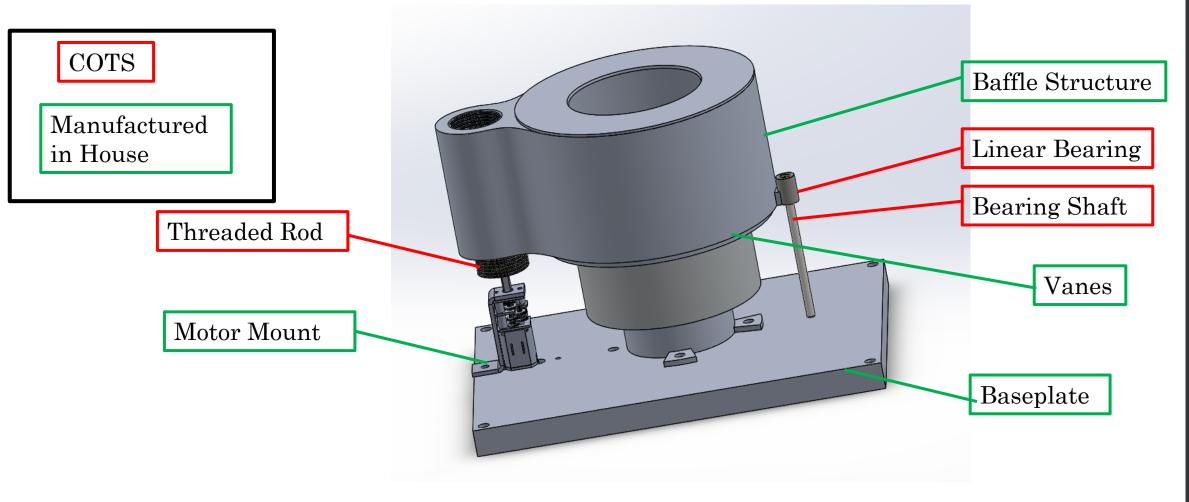
- Parts & Material
 - Not delivered by start of semester
- Schedule slip
 - As machining picks up for all of the teams, machines become less available

Manufacturing

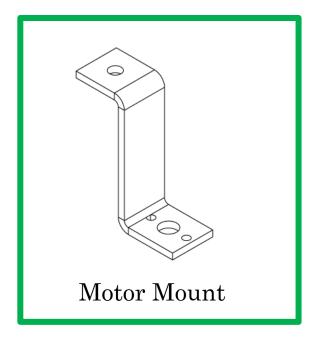
Baffle Overview

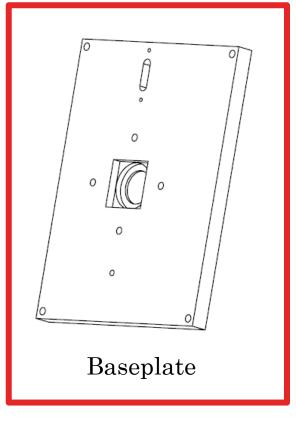


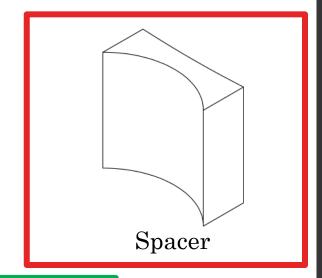
In House vs. COTS

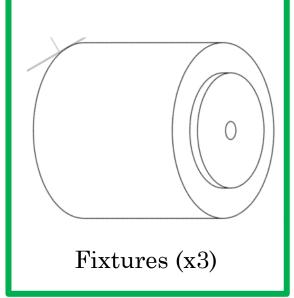


Other Pieces



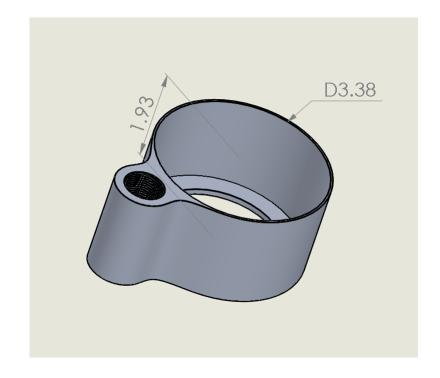






Top Section

Process	Time To complete
Drill holes for fixture attachment	1 hr
Use CNC mill to cut outside to size and shape	4 hrs
Use CNC mill to mill large radius circle	8 hrs
Use CNC mill to mill small radius circle (Shelf)	2 hrs
Use CNC mill to drill hole for threading	0.5 hrs
Thread drilled hole	1 hr
TOTAL	17 hrs

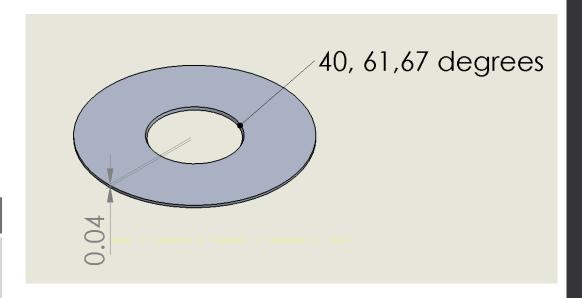


Main concerns

- Time intensive processes
- Many processes to be completed

Vanes

Operation	Time
Use CNC mill for outer diameter	0.5 hr
Use CNC lathe for inner diameter and angle	1 hr
TOTAL	1.5 hrs each



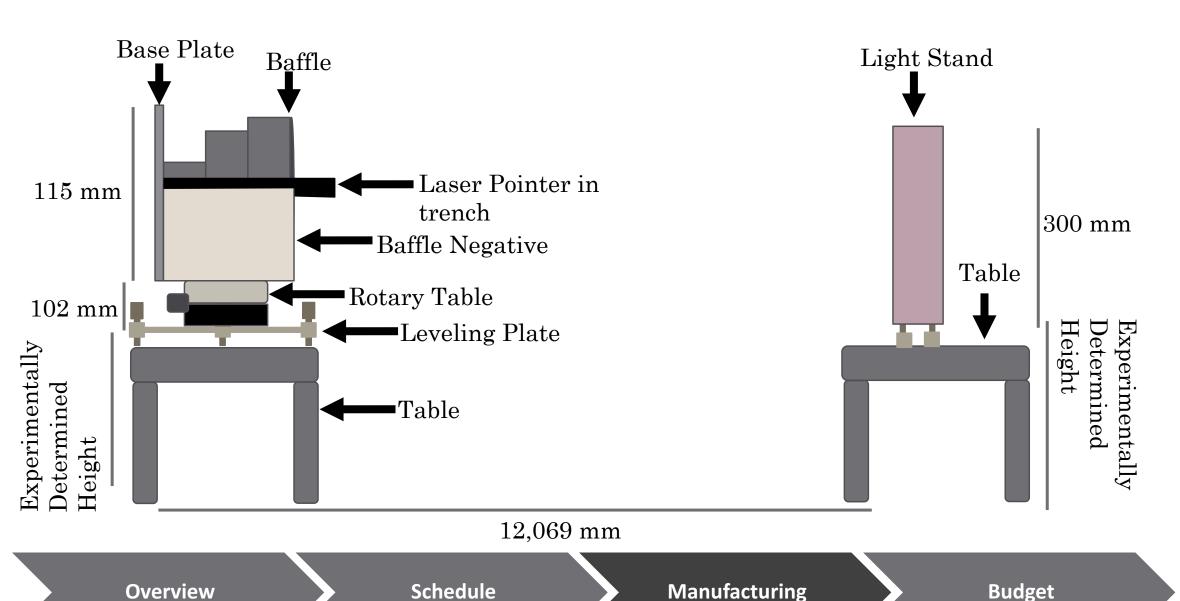
Main Concerns:

- Sheet metal
- Easy to bend or warp

Conclusion - Manufacturing

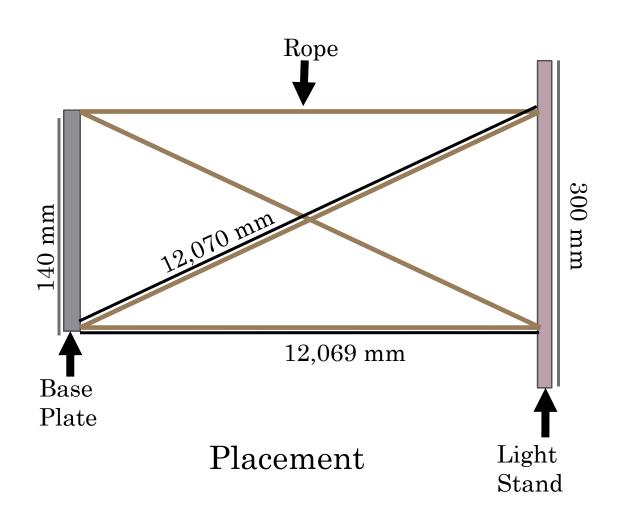
Part	Machine/process	Time remaining	Completion Date
Top Fixture	CNC Mill	0 hrs	2/2
Middle Fixture	CNC Lathe	0 hrs	1/30
Bottom Fixture	CNC Lathe	0 hrs	1/23
Top Baffle Section	CNC Mill	17 hrs	3/3
Middle Baffle Section	CNC Lathe	4 hrs	2/17
Bottom Baffle Section	CNC Lathe	4 hrs	2/17
Vanes (x3)	CNC Mill & Lathe	1.5 hrs each	3/3
Baseplate	CNC Mill	3 hrs	3/3
Motor Mount	Hand Mill & Metal Bender	0 hrs	1/31
TOTAL		32.5 hrs	All Complete By: 3/3

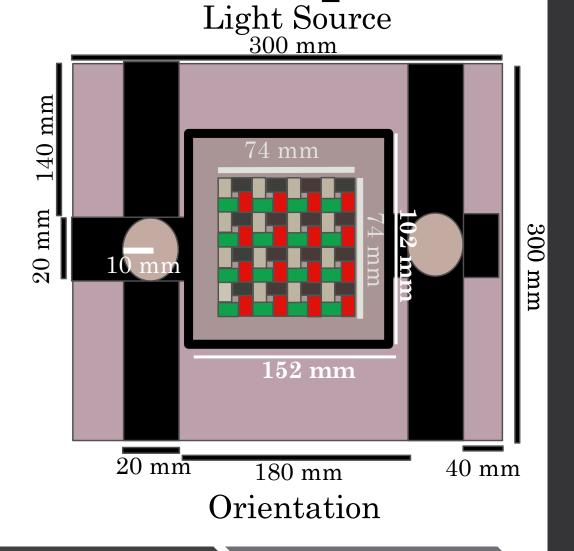
Testing Overview – Light Attenuation



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Placement/Orientation Set-up



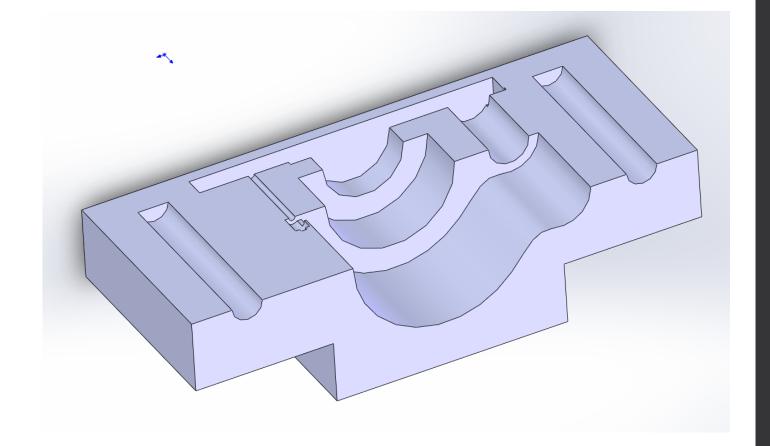


Calibration Test Tolerances

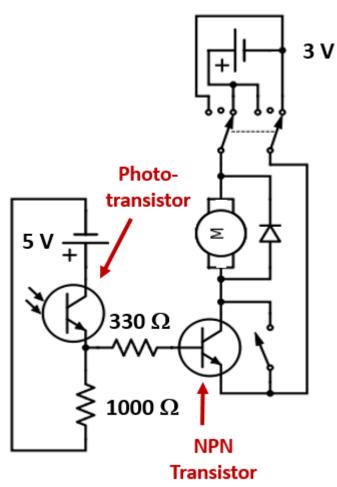
Part	Tolerance	Requirements
Rope (Distance)	$\pm 200mm$ changes sun's arc length by $< 0.01^{\circ}$	Apparent sun diameter = 0.5° Error: <2%
Laser (Orientation)	±20mm + Manufacturing Error changes Results Angle by 0.27°	Light Attenuation: Pre-obscuration Margin: 1.1° Obscuration Margin: 9.3°

Negative Support Structure

- Support Baffle Structure
- 4 Total Negatives
 - 2 Symmetrical
 - 2 Asymmetrical

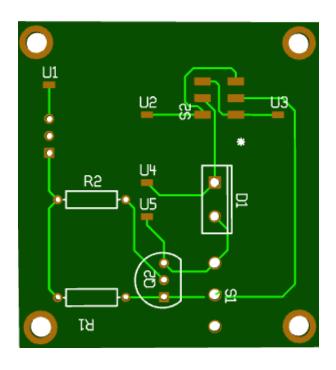


Motor Controller Circuit



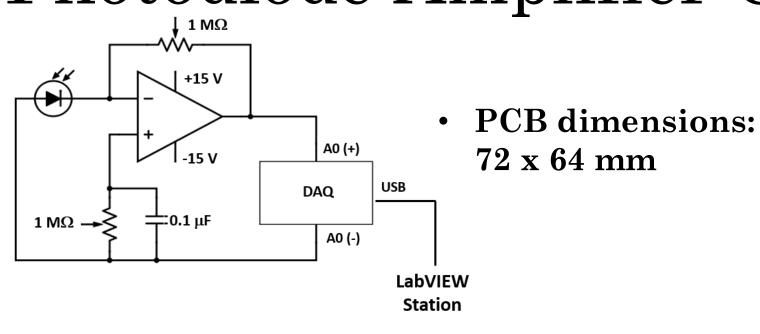
• PCB Dimensions: 46 x 49 mm

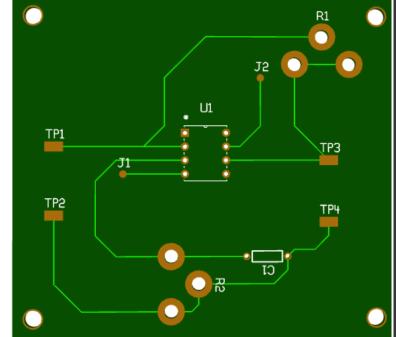
- One HW5P-1
 Phototransistor for BC337 NPN transistor base biasing
- One Jameco 22841
 DPDT center-off
 switch and one 76523
 SPST switch for baffle
 deployment reset



 One IN4007 flyback diode for NPN transistor protection from inductive kickback

Photodiode Amplifier Circuit

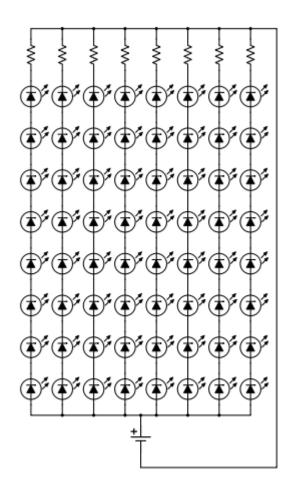




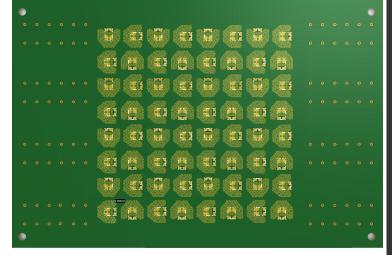
- Single 18 x 18 mm Hamamatsu S1337-21 Photodiode for light detection
- Two 1M Ω Variable Resistors and one 0.1 μF capacitor for amplification tuning and noise filtering
- Copper pours for additional noise reduction

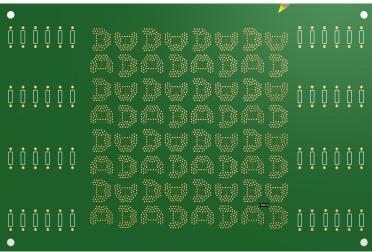
- LM741 Op-Amp for current-to-voltage amplification
- NI USB-6009 DAQ connected to computer station running a LabVIEW voltage module for data collection

LED Circuit



- PCB Dimensions: 152 x 102 mm
- 64 surface mounted Luxeon Rebel Color LEDS arranged in an 8 x 8 array
- LED Array Dimensions: 74 x 74 mm
- Forty-eight 2W, 2W resistors for power dissipation
- Enlarged thermal pads for heat dissipation (suggested by the manufacturer)





Electronics Summary

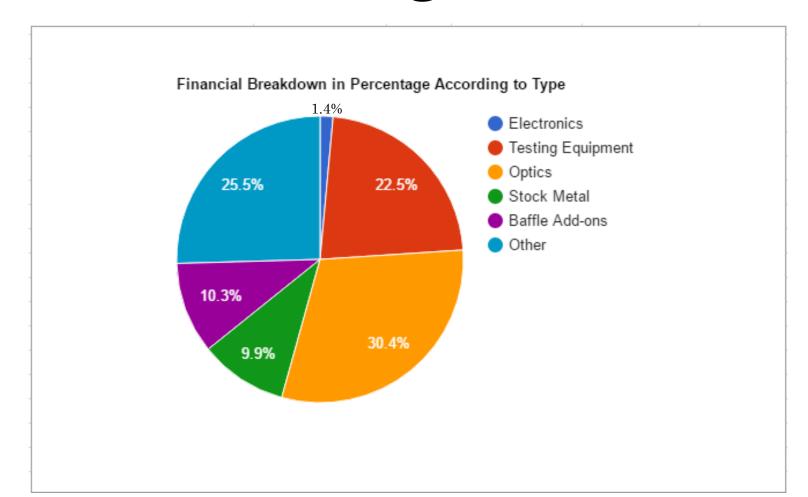
	Motor Controller Circuit	Photodiode Amp Circuit	LED Array
PARTS	Waiting on Hamamatsu photodiode – expected to ship end of February	All parts acquired	All parts acquired
CONCERNS	Small size of phototransistor makes breadboard testing difficult	None	Heat Dissipation - Mitigated by expanded thermal pads and short-duration power application Design Rule Check violations - Possible mitigation by recreating footprints manually – potentially very time consuming. Alternative solutions being investigated
PLAN	Print PCBs via Advanced Circuits once breadboard testing complete and all DRCs pass. Expected cost \$33/board. Expected turnaround 5 business days from order placement.		

Conclusion - Testing

Part	Machine/ Process	Time To Complete	Completion Date
PCB & Laser Support	Hand Mill	1 hr	3/10
Light Stand	Mill	2 hr	3/10
Leveling Plate	Mill	2 hr (CNC) 4 hr (Hand)	3/10
3-D Support (x4)	CNC Mill	4 hrs	3/17
Motor Controller Circuit	Outsourcing	5 hrs	3/3
Photodiode Amplifier Circuit	Outsourcing	5 hrs	3/3
LED Circuit	Outsourcing	5 hrs	3/3
TOTAL		38 hrs	3/17

Budget

Overall Budget



Electronics - \$37.94
Testing Equipment - \$587.19
Optics - \$792.00
Stock Metal - \$258.80
Baffle Add-Ons - \$269.32
Other - \$664.20

Sum - \$2,609.45

Margin - \$2,390.55

Financial Status

- All items (except 3) have arrived and are currently in team locker
 - The Si Photodiode, RapidEdge Filter, and the Aeroglaze Coating have all been ordered and will arrive within the month
- Future cost include:
 - Re-ordering items/stock material if necessary
 - Application of coating on baffle
 - Batteries for laser
 - Material for black felt tunnel
 - Material for 3-D support
 - High density foam from bottle rocket excess supplies

Questions?

Backup Slides

Project Assumptions & Levels of

Success

- Design is proof of concept
 - Need not be space grade
- Focus on attenuating light from Sun

• Spacecraft will be in L.E.O.

- From spacecraft bus:
 - Voltage available: 28 V
 - · Current available: 2.5 Amps
 - Power available: 70 Watts

	TIER 1	TIER 2
DEPLOY BAFFLE (FR1)	Manual Deployment	Electronic deployment with a wired connection
STOWED BAFFLE VOLUME (FR2)	Constrained by: 175 mm width 175 mm length 50 mm height	Constrained by: 125 mm width 125 mm length 50 mm height
BAFFLE MASS (FR3)	<500 grams	<300 grams
BAFFLE LIGHT EXCLUSION (FR4)	40 degree light exclusion angle	30 degree light exclusion angle

Overview Schedule Budget

Requirements

- •FR1: Baffle shall be deployable
 - DR1.1: Deployable using 28V
 - DR1.2: Full deployment ground testing shall be conducted
- •FR2: Baffle shall fit within volume constraints
 - DR 2.1: Fit within 125x125x50mm box
- •FR3: Baffle shall adhere to mass constraints
 - DR 3.1: Weight less than 300g
- •FR4: Baffle shall attenuate light
 - DR 4.1: Ground testing shall be done to determine light obscuration
 - DR 4.2: 99.9% light attenuation at 30 degrees
 - DR 4.3: Baffle shall have a Pre-Obscuration angle of $\geq 10^{\circ}$

Overview Schedule Budget 30

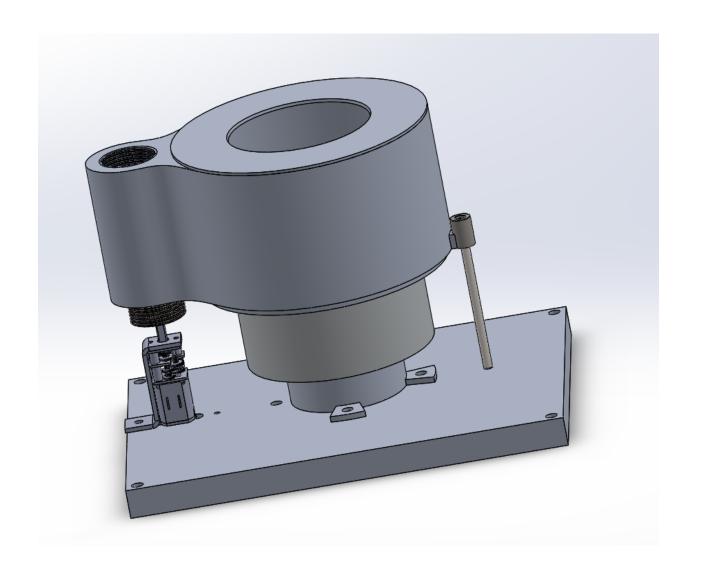
Manufacturing Safety Status

- Risk Mitigation for Machine Shop
 - Personal protective equipment
 - Proper clothing
 - Proper disposal of materials
 - Clean up after machine use
 - Supervision of machining where necessary

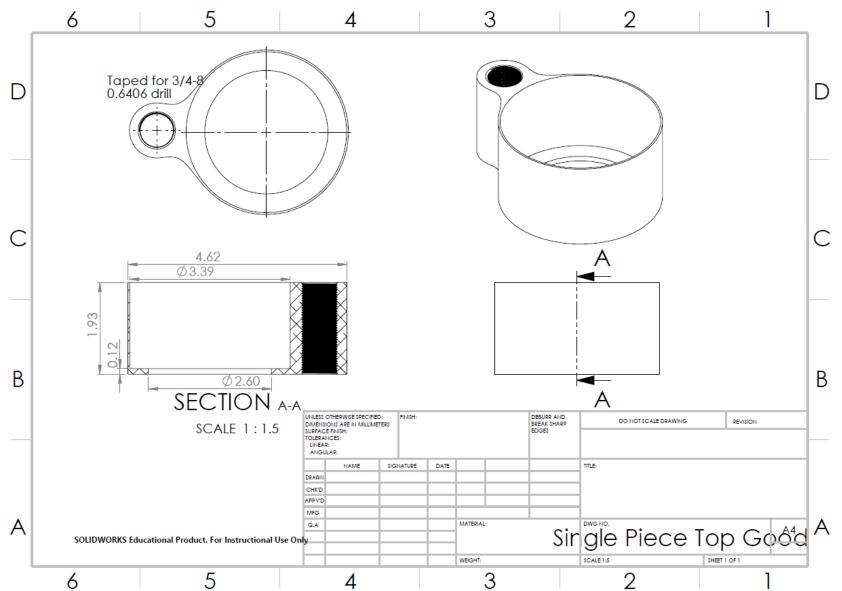
Category Breakdown

- Electronics
 - Includes PC board, resistors, and other small components
- Testing Equipment
 - Includes LEDS, lasers, and rotary table
- Optics
 - Includes filter and photodiode
- Stock Metal
 - Includes Aluminum 2024-T4
- Baffle Add-Ons
 - · Includes thread tap, bearing, shaft, motor, and gear
- Other
 - · Includes epoxy, adhesive, and shipping costs

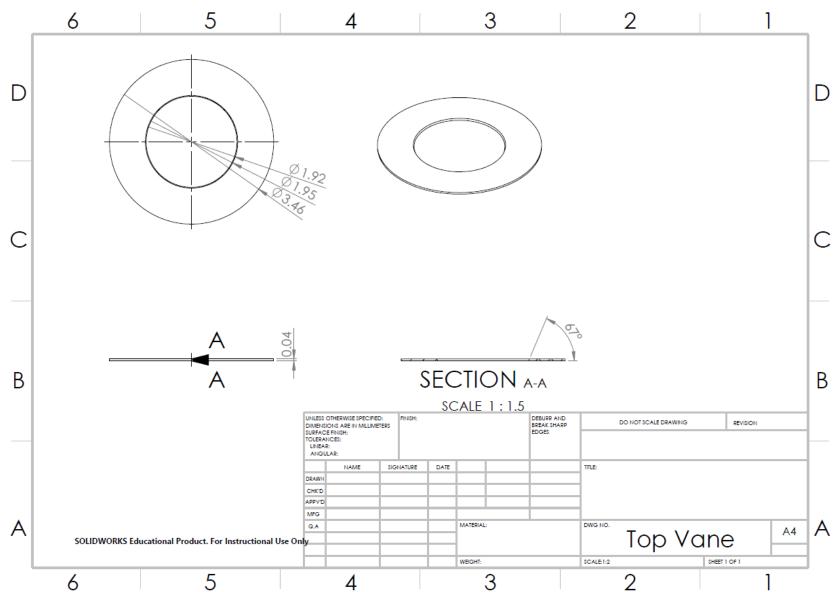
Full Baffle



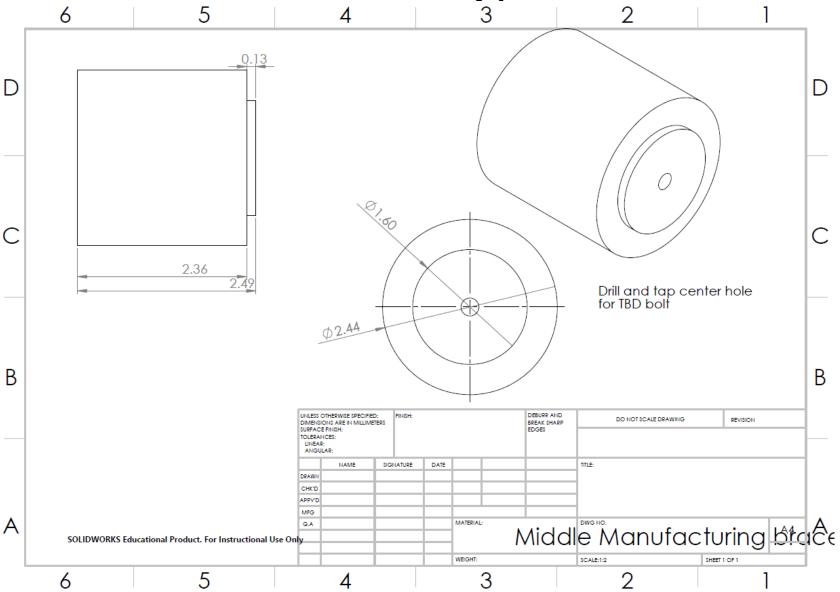
Top Tier



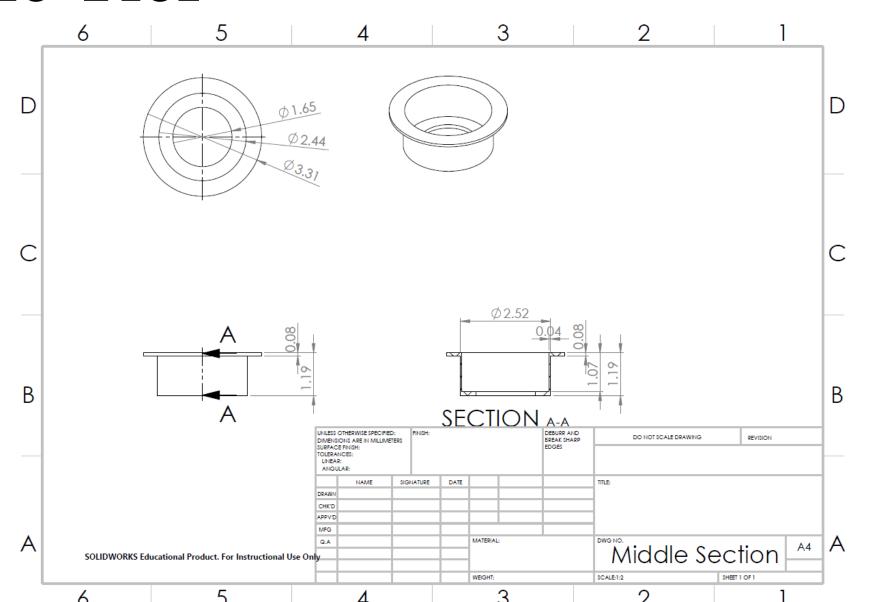
Top Vane



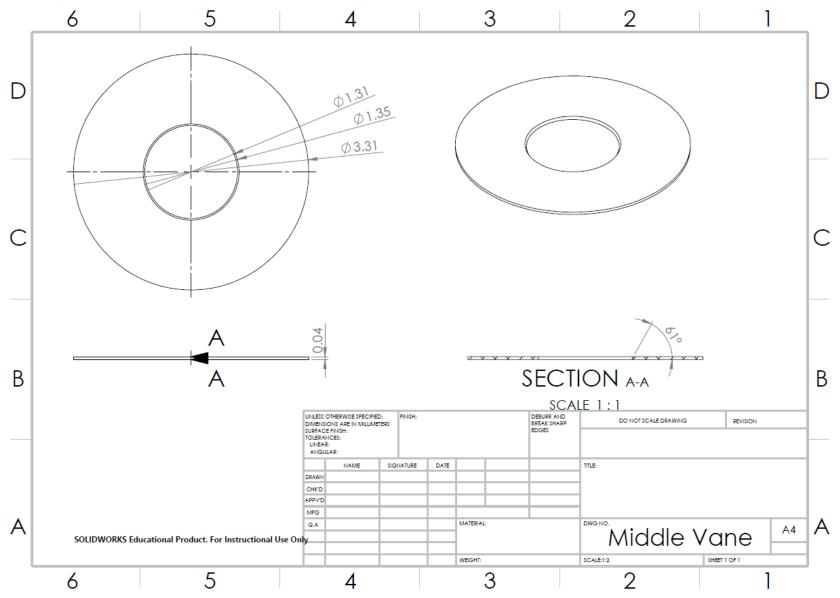
Middle Manufacturing Brace



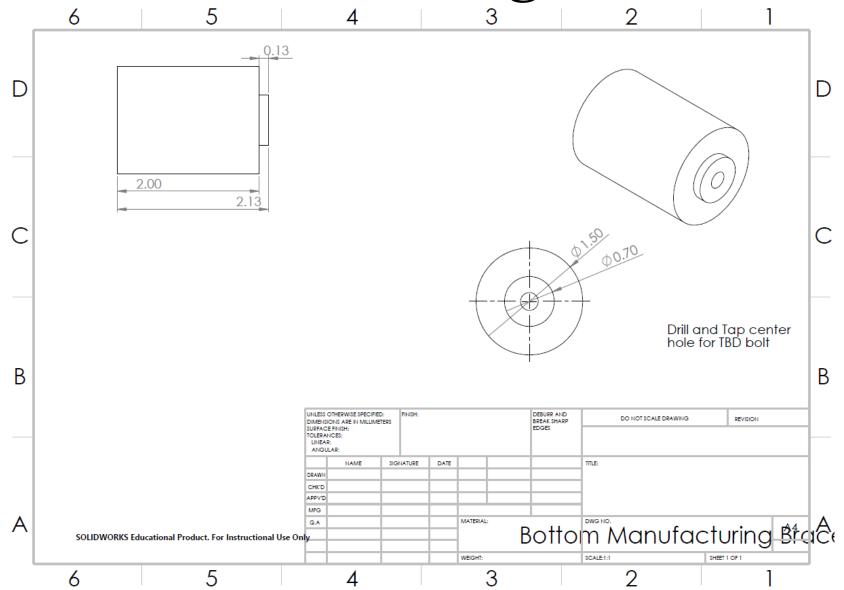
Middle Tier



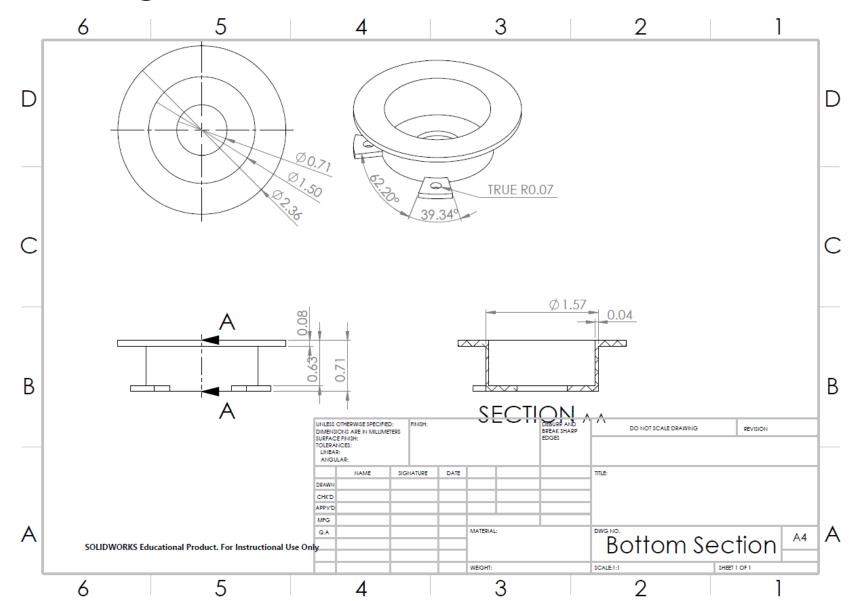
Middle Vane



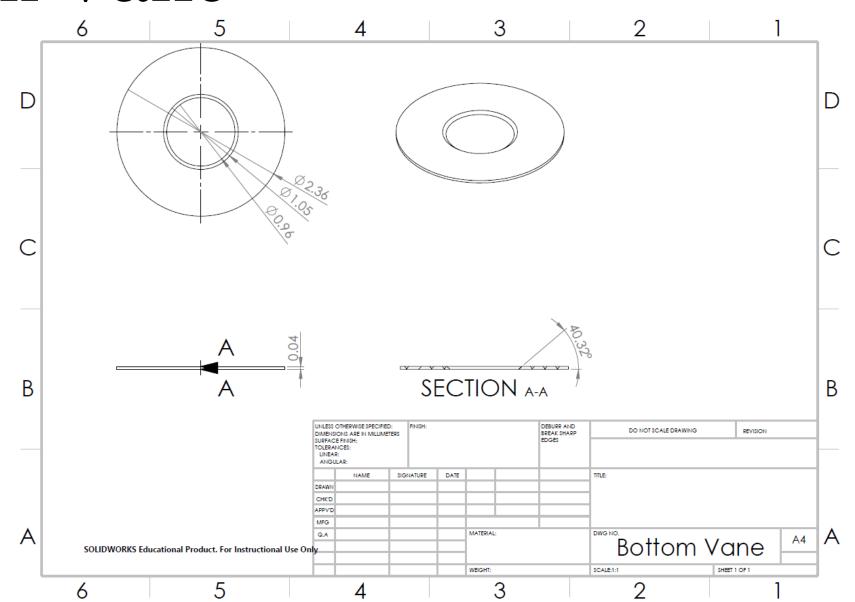
Bottom Manufacturing Brace



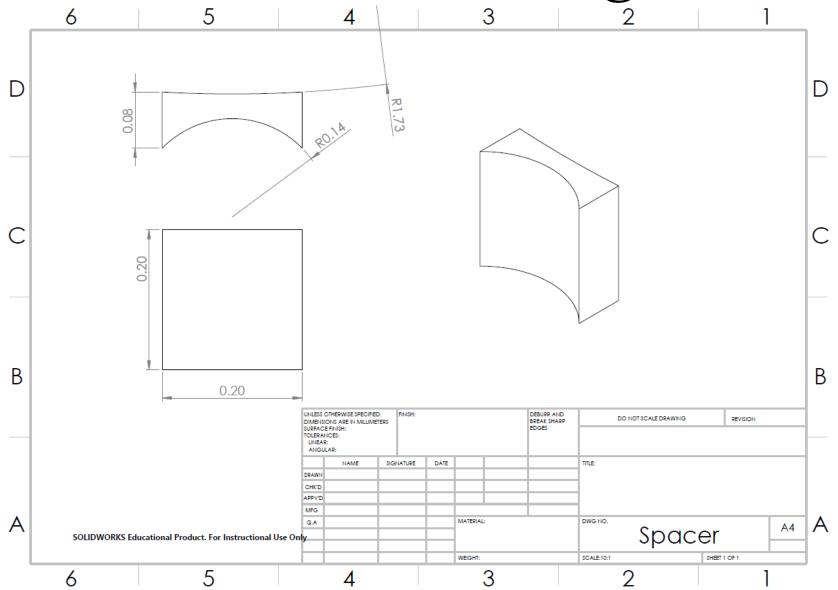
Bottom Tier



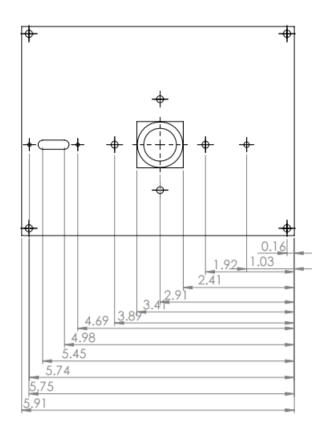
Bottom Vane

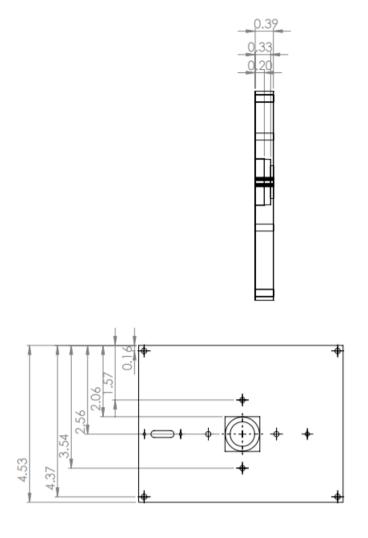


Spacer for Linear Bearing

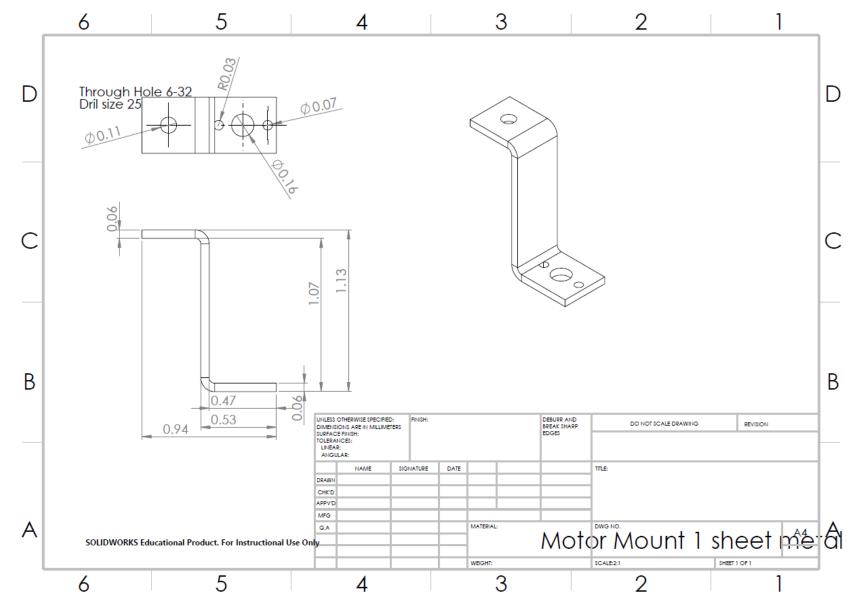


Base Plate

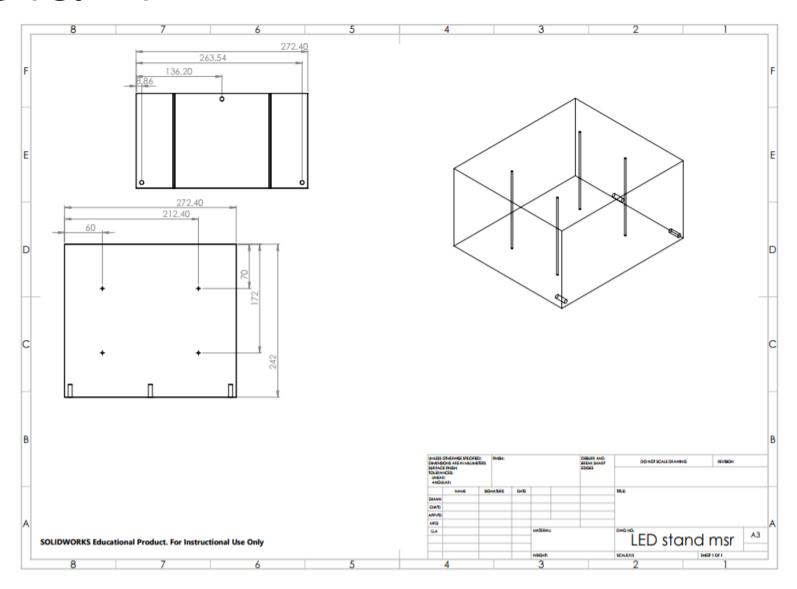




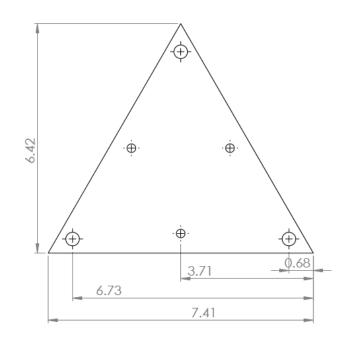
Sheet Metal Motor Mount

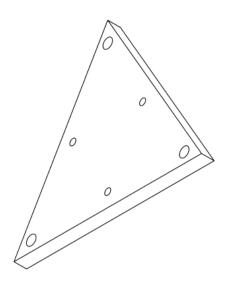


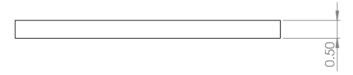
LED Stand



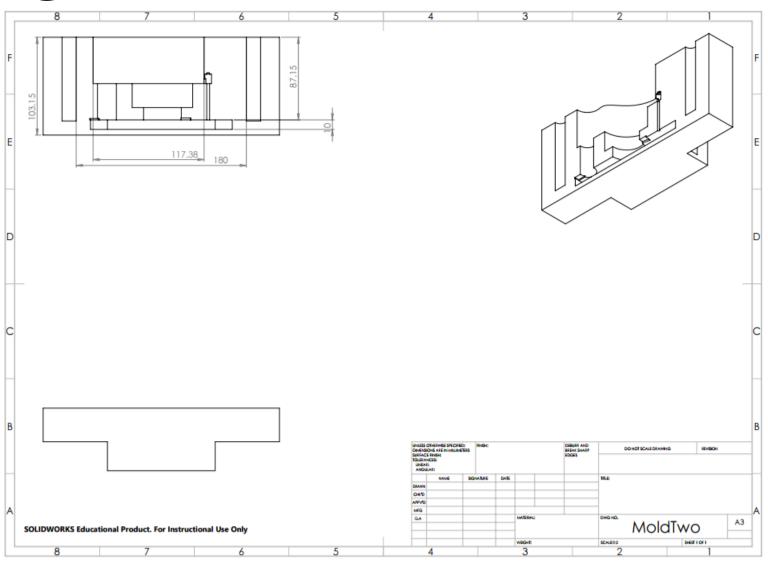
Rotary Table Level Table







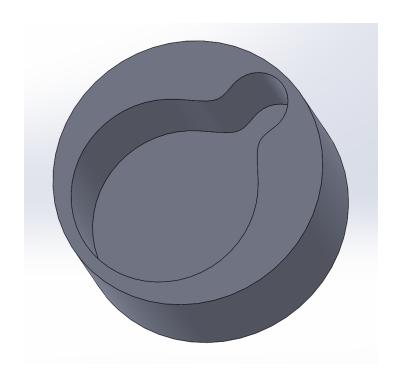
CAD Negative



Baffle Fixtures

Top Section







Machine	Time Remaining
CNC Mill	0 hrs

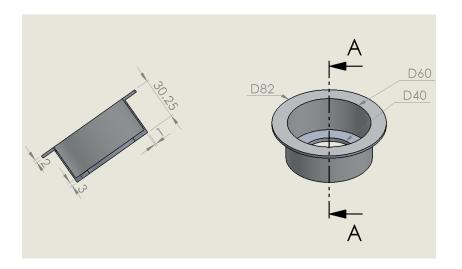
MachineTime RemainingCNC Lathe0 hrs

Overview Schedule Manufacturing Budget

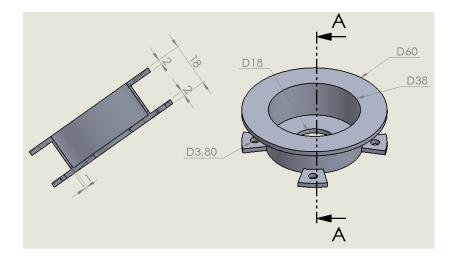
56

Baffle Sections

Middle Section



Bottom Section



Machine	Time Remaining
CNC Lathe	4 hrs

Machine Time Remaining
CNC Lathe 4 hrs

Baseplate & Motor Mount

Baseplate

Motor Mount

Machine	Time Remaining
CNC Mill	3 hrs

Machine	Time Remaining
Hand Mill & Metal Bender	0 hrs

Overview Schedule Manufacturing Budget

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Light Stand & PCB & Laser Support

Light Stand

PCB & Laser Support

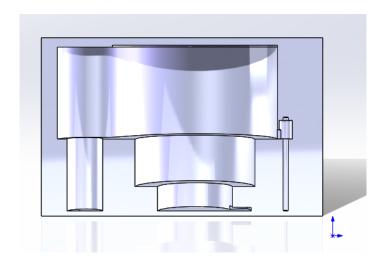
Machine	Time Remaining	Machi	ne Time Remaining
	2 hrs	Hand N	Mill 1 hr
Overview	Schedule	Manufacturing	Budget

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Leveling Plates & 3-D Supports

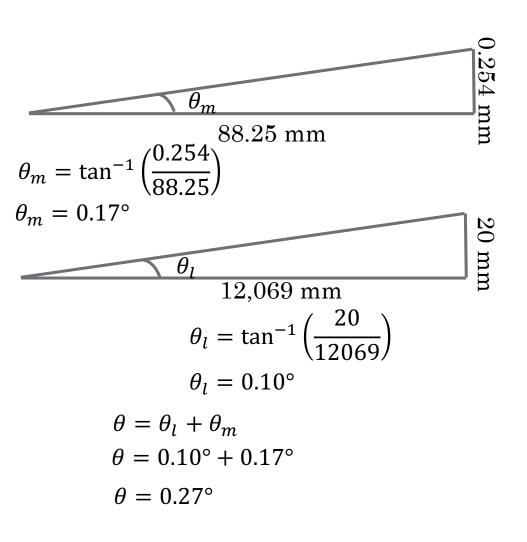
Leveling Plates

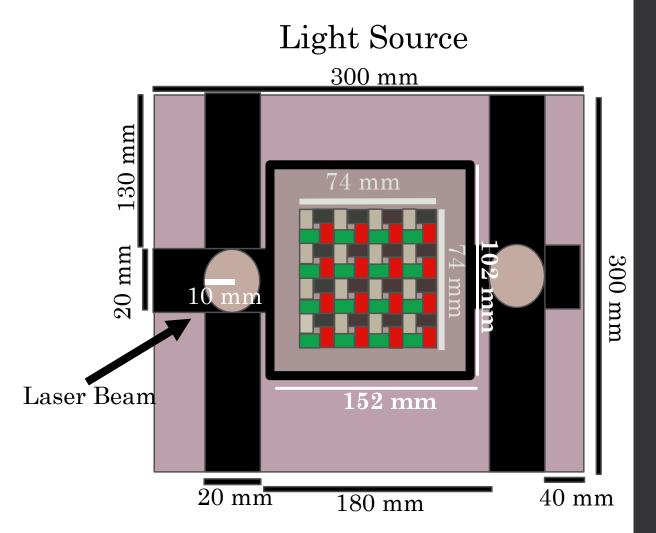
3-D Supports (x4)



Machine	Time Remaining			Machine	Time Remai	ning
	hr	'S			hrs	
Overview		Schedule	>	Manufacturing	Budget	

Orientation Verification





Need for Black Felt Room

Problem:

Dark room has many reflective surfaces

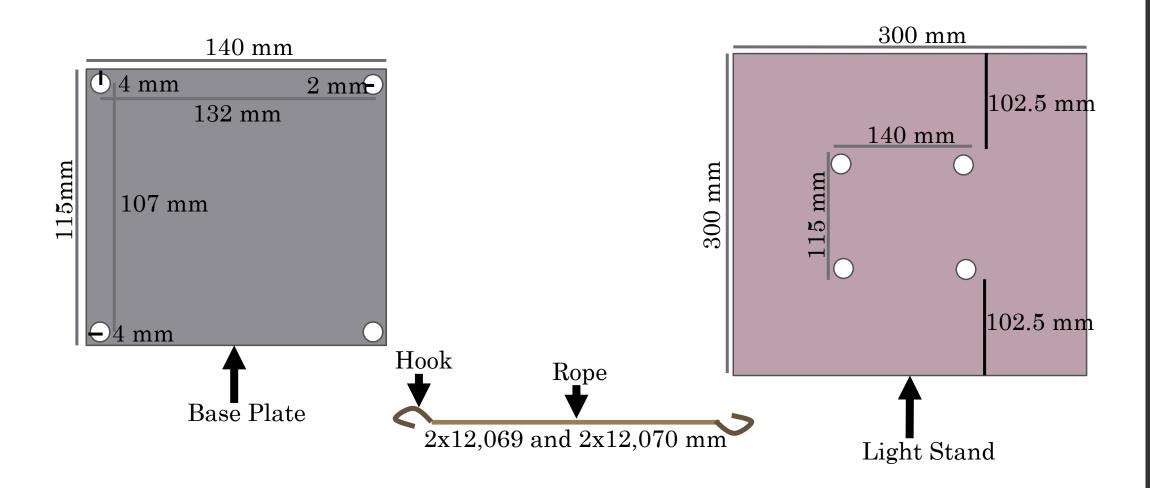
- Floor/Ceiling
- Walls
- Pipes

Solution:

Covering Dark room surfaces in black felt, which will help block the reflectiveness of the surfaces underneath



Placement Set-up



Testing Safety Status

Health and Safety	Equipment and Lab Failure
15% Complete, still compiling hazards	10% Complete, lab design is still changing

Further Steps to Take:

- Continue compiling hazards to health and safety as well as equipment and our lab hallway.
- Assemble checklists in parallel with testing procedure.
- Delegate out requests for input on failure modes as time demands.
- Be pessimistic.
- Regularly reach out to the PAB.

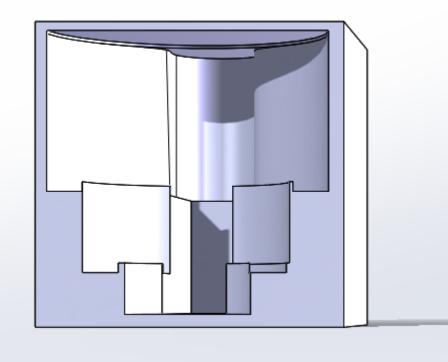
Negative Support Structure

-The purpose of this structure is to hold the baffle in position for optical testing

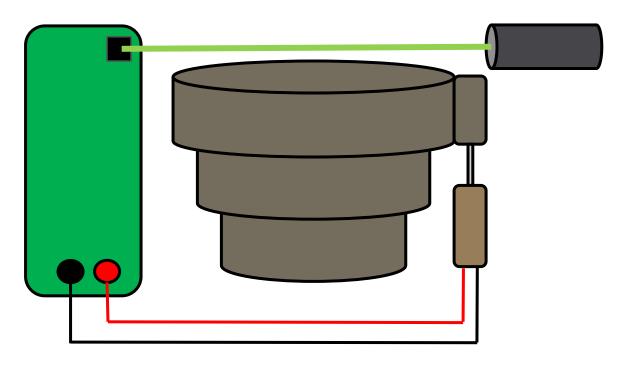
-Two Support structure manufacturing methods will be explored

1) A 3D printed design, the Solidworks file was made from the CAD of the baffle itself will include pieces that must be cut away 2)A high density foam block cut away to fit the baffle and hold it in place

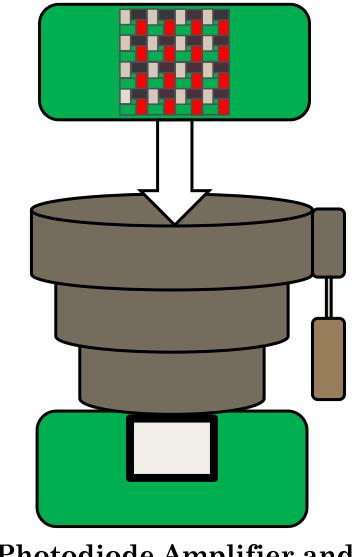
Once one of each is made and checked for accuracy, one of the methods will be chosen to make the remaining 3 support structures



Electronics Overview

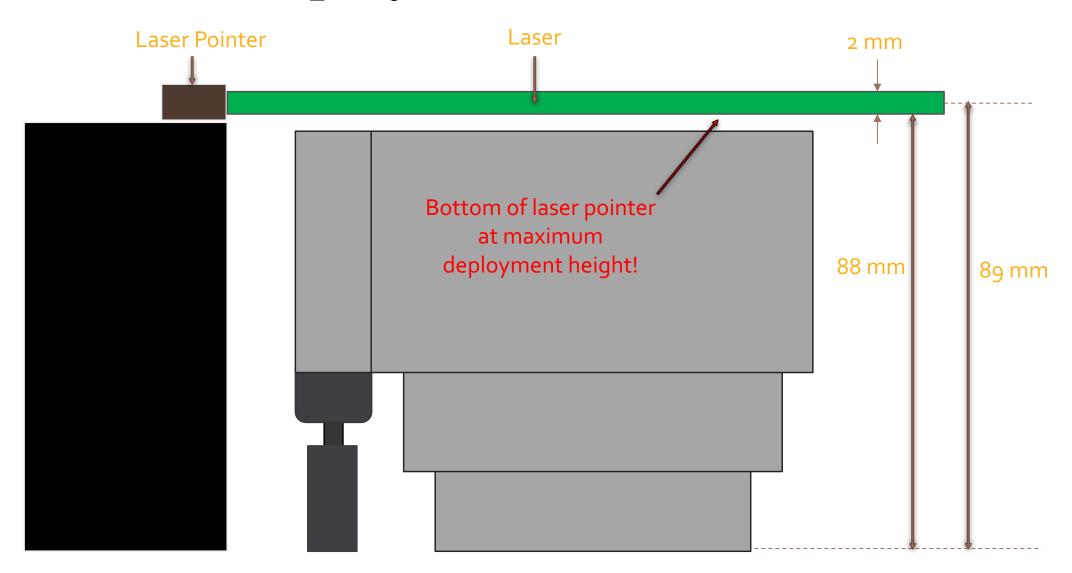


Motor Controller Circuit



Photodiode Amplifier and LED Circuits

Maximum Deployment



Deployment Test Set PCB Support "Beam of Light" Laser Pointer Laser Pointer Support "Beam of Light" **PCB Support** Laser Pointer Phototransistor Laser Pointer Support